



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Applicant of : Group Art Unit: 2815
 Khandros et al.

Continued Prosecution Application :
 of Serial No. 08/984,615 :
 Examiner: S. Clark

Filed: December 3, 1997 : Date: September 10, 1998

For: **SEMICONDUCTOR CHIP PACKAGE** :
WITH CENTER CONTACTS :
 X Batch No. F86

Assistant Commissioner For Patents
 Box Patent Application
 Washington, D.C. 20231

PRELIMINARY AMENDMENT

Sir:

Prior to calculating the filing fee in the Continued Prosecution Application filed contemporaneously herewith, please amend the application as follows:

In the Claims:

Insert new claims 71-76 as follows:

71. A chip assembly as claimed in claim 61 wherein the contact leads include wire bonds.

72. A semiconductor chip assembly comprising:

(a) a semiconductor chip having a front surface defining the top of the chip, said front surface including a central region and a peripheral region surrounding said central region, whereby said central region is disposed inwardly of said peripheral region, said chip having central contacts disposed in said central region of said front surface;

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 RECEIVED
 G. Stanley
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